

Title (en)

CONDUCTOR CONNECTING MODULE FOR PRINTED CIRCUIT BOARDS

Title (de)

ADERANSCHLUSSMODUL FÜR LEITERPLATTEN

Title (fr)

MODULE DE CONNEXION DE CONDUCTEURS POUR DES CARTES A CIRCUITS IMPRIMES

Publication

EP 1649549 A1 20060426 (DE)

Application

EP 04740236 A 20040624

Priority

- EP 2004006821 W 20040624
- DE 10333913 A 20030725

Abstract (en)

[origin: US2007111555A1] The invention relates to a conductor connecting module for printed circuit boards, comprising a housing in which contact elements are disposed. Said contact elements have a first contact area that is configured as an insulation displacement contact, and a second contact area that is configured as a solderable contact pin. The contact pins are disposed at a right angle to the insulation displacement contacts so that the insulation displacement contacts, in the mounted state, lie in a plane parallel to the printed circuit board.

IPC 1-7

H01R 12/04; **H01R 4/24**

IPC 8 full level

H01R 4/24 (2006.01); **H01R 12/04** (2006.01); **H01R 12/55** (2011.01); **H01R 12/71** (2011.01); **H01R 4/02** (2006.01)

CPC (source: EP KR US)

H01R 12/515 (2013.01 - EP US); **H01R 12/52** (2013.01 - KR); **H01R 12/72** (2013.01 - KR); **H01R 4/023** (2013.01 - EP US); **H01R 4/2429** (2013.01 - EP US); **H01R 12/7064** (2013.01 - EP US)

Citation (search report)

See references of WO 2005020376A1

Designated contracting state (EPC)

AT BE BG CH CY CZ DE DK EE ES FI FR GB GR HU IE IT LI LU MC NL PL PT RO SE SI SK TR

DOCDB simple family (publication)

US 2007111555 A1 20070517; **US 7591654 B2 20090922**; AT E344540 T1 20061115; AU 2004302244 A1 20050303; AU 2004302244 B2 20091022; BR PI0412831 A 20060926; CA 2527353 A1 20050303; CA 2527353 C 20100316; CN 1830119 A 20060906; DE 10333913 A1 20050224; DE 502004001921 D1 20061214; EP 1649549 A1 20060426; EP 1649549 B1 20061102; ES 2274465 T3 20070516; JP 2006528828 A 20061221; KR 100840161 B1 20080623; KR 20060030488 A 20060410; MX PA06000751 A 20060330; PL 1649549 T3 20070330; TW 200507361 A 20050216; TW I261389 B 20060901; WO 2005020376 A1 20050303

DOCDB simple family (application)

US 56574004 A 20040624; AT 04740236 T 20040624; AU 2004302244 A 20040624; BR PI0412831 A 20040624; CA 2527353 A 20040624; CN 200480021495 A 20040624; DE 10333913 A 20030725; DE 502004001921 T 20040624; EP 04740236 A 20040624; EP 2004006821 W 20040624; ES 04740236 T 20040624; JP 2006521409 A 20040624; KR 20057025422 A 20051230; MX PA06000751 A 20040624; PL 04740236 T 20040624; TW 93121929 A 20040722